

General Description

The MAX13485E/MAX13486E +5V, half-duplex, ±15kV ESD-protected RS-485 transceivers feature one driver and one receiver. These devices include fail-safe circuitry, guaranteeing a logic-high receiver output when receiver inputs are open or shorted. The receiver outputs a logichigh if all transmitters on a terminated bus are disabled (high impedance). The MAX13485E/MAX13486E include a hot-swap capability to eliminate false transitions on the bus during power-up or live-insertion.

The MAX13485E features reduced slew-rate drivers that minimize EMI and reduce reflections caused by improperly terminated cables, allowing error-free transmission up to 500kbps. The MAX13486E driver slew rate is not limited, allowing transmit speeds up to 16Mbps.

The MAX13485E/MAX13486E feature a 1/4-unit load receiver input impedance, allowing up to 128 transceivers on the bus. These devices are intended for half-duplex communications. All driver outputs are protected to ±15kV ESD using the Human Body Model. The MAX13485E/ MAX13486E are available in 8-pin SO and space-saving 8-pin µDFN packages. The devices operate over the extended -40°C to +85°C temperature range.

Applications

Utility Meters Industrial Controls Industrial Motor Drives Automated HVAC Systems

Features

- ♦ +5V Operation
- ♦ True Fail-Safe Receiver While Maintaining **EIA/TIA-485 Compatibility**
- **♦** Hot-Swappable for Telecom Applications
- ♦ Enhanced Slew-Rate Limiting Facilitates Error-Free Data Transmission (MAX13485E)
- ♦ High-Speed Version (MAX13488E) Allows for **Transmission Speeds Up to 16Mbps**
- ♦ Extended ESD Protection for RS-485/RS-422 I/O Pins ±15kV Using Human Body Model
- ♦ 1/4 Unit Load, Allowing Up to 128 Transceivers on the Bus
- ♦ Available in Space-Saving 8-Pin µDFN or Industry Standard 8-Pin SO Packages

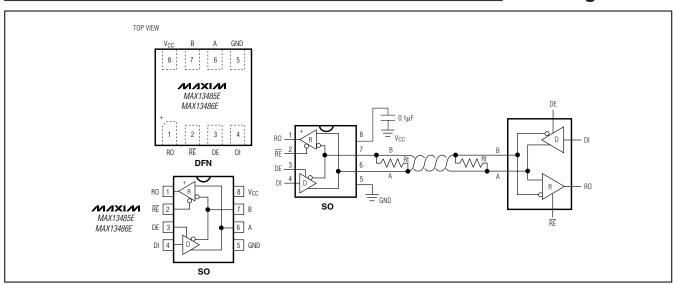
Ordering Information/ Selector Guide

PART	PIN- PACKAGE	SLEW-RATE LIMITED	PKG CODE
MAX13485EELA+T	8 µDFN	Yes	L822-1
MAX13485EESA+	8 SO	Yes	S8-2
MAX13486EELA+T	8 µDFN	No	L822-1
MAX13486EESA+	8 SO	No	S8-2

⁺Denotes a lead-free package.

Note: All devices are specified over the -40°C to +85°C operating temperature range.

Pin Configurations



NIXIN

Maxim Integrated Products 1

ABSOLUTE MAXIMUM RATINGS

(All voltages referenced to GND.)	
V _{CC}	+6V
DE, RE, DI	0.3V to +6V
A, B	8V to 13V
Short-Circuit Duration (RO, A, B) to GND	Continuous
Continuous Power Dissipation ($T_A = +70$ °C)	
8-Pin SO (derate 5.9mW/°C above +70°C)	471mW
8-Pin µDFN (derate 4.8mW/°C above +70°C)	380.6mW

Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s	s)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(VCC = +5V ±5%, T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at V_{CC} = +5V and T_A = +25°C.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIO	ONS	MIN	TYP	MAX	UNITS
DRIVER	•			•			
		$R_{DIFF} = 100\Omega$, Figure 1		2.0		Vcc	
Differential Driver Output	V _{OD}	$R_{DIFF} = 54\Omega$, Figure 1		1.5			V
		No load				V _{CC}	
Change in Magnitude of Differential Output Voltage	ΔV _{OD}	$R_{\text{DIFF}} = 100\Omega \text{ or } 54\Omega, \text{ Fig}$	ure 1 (Note 3)			0.2	V
Driver Common-Mode Output Voltage	Voc	$R_{\text{DIFF}} = 100\Omega \text{ or } 54\Omega, \text{ Fig}$	ure 1		V _{CC}	3	V
Change in Magnitude of Common-Mode Voltage	ΔV _{OC}	$R_{\text{DIFF}} = 100\Omega \text{ or } 54\Omega, \text{ Fig}$	ure 1 (Note 3)			0.2	V
Input-High Voltage	VIH	DI, DE, RE		2.0			V
Input-Low Voltage	VIL	DI, DE, RE				0.8	V
Input Current	I _{IN}	DI, DE, RE				±1	μΑ
Driver Short-Circuit Output	loop	0V ≤ V _{OUT} ≤ +12V	+50		+250	mA	
Current (Note 4)	losp	-7V ≤ V _{OUT} ≤ 0V		-250		-50	IIIA
Driver Short-Circuit Foldback	loops	$(V_{CC} - 1V) \leq V_{OUT} \leq +12V_{OUT}$	V	20			mA
Output Current Note 3)	IOSDF	-7V <u><</u> V _{OUT} <u><</u> 0V				-20	IIIA
RECEIVER							
Input Current (A and D)	1. 5	DE = GND, V _{CC} = GND	$V_{IN} = +12V$			250	
Input Current (A and B)	I _{A, B}	or +5V	$V_{IN} = -7V$	-200			μΑ
Receiver-Differential-Threshold Voltage	VTH	-7V ≤ V _{CM} ≤ +12V		-200		-50	mV
Receiver Input Hysteresis	ΔVTH	$V_A + V_B = 0V$			25		mV
Output-High Voltage	V _{OH}	I _O = -1.6mA, V _A - V _B > V _T	Ή	V _{CC} - 1.5			V

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = +5V \pm 5\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V_{CC} = +5V \text{ and } T_A = +25^{\circ}C.)$ (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output-Low Voltage	Vol	$I_O = 1mA$, $V_A - V_B < -V_{TH}$			0.4	V
Tri-State Output Current at Receiver	lozr	0V ≤ V _O ≤ V _{CC}			±1	μΑ
Receiver Input Resistance	RIN	-7V ≤ V _{CM} ≤ +12V	48			kΩ
Receiver-Output Short-Circuit Current	IOSR	0V ≤ V _{RO} ≤ V _{CC}	±7		±95	mA
POWER SUPPLY	•					
Supply Voltage	Vcc		4.75		5.25	V
Supply Current	Icc	$DE = 1$, $\overline{RE} = 0$, no load			4.5	mA
Shutdown Supply Current	ISHDN	$DE = 0, \overline{RE} = 1$			10	μΑ
ESD PROTECTION						
ESD Protection (A, B)		Air Gap Discharge IEC61000-4-2 (MAX13485E)		±15		kV
		Human Body Model		±15]
ESD Protection (All Other Pins)		Human Body Model		±2		kV

SWITCHING CHARACTERISTICS—MAX13485E

 $(V_{CC} = +5V \pm 5\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$ Typical values are at $V_{CC} = +5V \text{ and } T_A = +25^{\circ}C.)$ (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS		
DRIVER								
Driver Propagation Dalay	tDPLH	Double 540 Ct. FOol Figures 2 and 2	200		1000			
Driver Propagation Delay	tdphl	$R_{DIFF} = 54\Omega$, $C_L = 50pF$, Figures 2 and 3	200		1000	ns		
Driver-Differential Output Rise or	tHL	RDIFF = 54Ω , CL = 50 pF, Figures 2 and 3	250		900	ns		
Fall Time	t _{LH}	11DIFF = 3432, GL = 30pr , rigures 2 and 3	250		900	115		
Driver-Differential Output Skew ItDPLH - tDPHLI	tdskew	R_{DIFF} = 54 Ω , C_{L} = 50pF, Figures 2 and 3			140	ns		
Maximum Data Rate			500			kbps		
Driver Enable to Output High	tDZH	Figures 4 and 5			2500	ns		
Driver Enable to Output Low	t _{DZL}	Figures 4 and 5			2500	ns		
Driver Disable Time from High	tDHZ	Figures 4 and 5			100	ns		
Driver Disable Time from Low	t _{DLZ}	Figures 4 and 5			100	ns		
Driver Enable from Shutdown to Output High	t _{DZH} (SHDN)	Figures 4 and 5			5500	ns		
Driver Enable from Shutdown to Output Low	t _{DZL} (SHDN)	Figures 4 and 5			5500	ns		
Time to Shutdown	tshdn		50	340	700	ns		
RECEIVER	RECEIVER							
Receiver Propagation Delay	trplh	C _L = 15pF, Figures 6 and 7			80	ns		
Theceiver i Topagation Delay	trphl	OL - 10pr, Figures 6 and 7			80	110		
Receiver Output Skew	trskew	C _L = 15pF, Figure 7			13	ns		
Maximum Data Rate			500			kbps		

SWITCHING CHARACTERISTICS—MAX13485E (continued)

 $(V_{CC} = +5V \pm 5\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$ Typical values are at $V_{CC} = +5V \text{ and } T_A = +25^{\circ}C.)$ (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Receiver Enable to Output High	trzh	Figure 8			50	ns
Receiver Enable to Output Low	t _{RZL}	Figure 8			50	ns
Receiver Disable Time from High	t _{RHZ}	Figure 8			50	ns
Receiver Disable Time from Low	t _{RLZ}	Figure 8			50	ns
Receiver Enable from Shutdown to Output High	[†] RZH(SHDN)	Figure 8			2200	ns
Receiver Enable from Shutdown to Output Low	tRZL(SHDN)	Figure 8			2200	ns
Time to Shutdown	tshdn		50	340	700	ns

SWITCHING CHARACTERISTICS—MAX13486E

(V_{CC} = +5V ±5%, T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at V_{CC} = +5V and T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS		
DRIVER								
Driver Propagation Delay	tDPLH	$R_{\text{DIFF}} = 54\Omega$, $C_{\text{L}} = 50\text{pF}$, Figures 2 and 3			50			
	tdphl	$\frac{1}{2}$ $\frac{1}$			50	ns		
Driver Differential Output Rise or	t _{HL}	$R_{DIFF} = 54\Omega$, $C_L = 50pF$, Figures 2 and 3			15	ns		
Fall Time	t _{LH}	11DIFF = 3432, OL = 30pi , i iguies 2 and 3			15	113		
Differential Driver Output Skew ItDPLH - tDPHLI	tdskew	R_{DIFF} = 54 Ω , C_{L} = 50pF, Figures 2 and 3			8	ns		
Maximum Data Rate			16			Mbps		
Driver Enable to Output High	tdzh	Figures 4 and 5			50	ns		
Driver Enable to Output Low	tDZL	Figures 4 and 5			50	ns		
Driver Disable Time from High	tDHZ	Figures 4 and 5			50	ns		
Driver Disable Time from Low	t _{DLZ}	Figures 4 and 5			50	ns		
Driver Enable from Shutdown to Output High	t _{DZH} (SHDN)	Figures 4 and 5			2200	ns		
Driver Enable from Shutdown to Output Low	t _{DZL} (SHDN)	Figures 4 and 5			2200	ns		
Time to Shutdown	tshdn		50	340	700	ns		
RECEIVER	RECEIVER							
Desciver Proposition Delay	trplh	C 15pE Figures 6 and 7			80	ns		
Receiver Propagation Delay	trphl	C _L = 15pF, Figures 6 and 7			80	115		
Receiver Output Skew	trskew	C _L = 15pF, Figure 7			13	ns		
Maximum Data Rate			16			Mbps		

SWITCHING CHARACTERISTICS—MAX13486E (continued)

 $(V_{CC} = +5V \pm 5\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$ Typical values are at $V_{CC} = +5V \text{ and } T_A = +25^{\circ}C.)$ (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Receiver Enable to Output High	trzh	Figure 8			50	ns
Receiver Enable to Output Low	t _{RZL}	Figure 8			50	ns
Receiver Disable Time from High	tRHZ	Figure 8			50	ns
Receiver Disable Time from Low	t _{RLZ}	Figure 8			50	ns
Receiver Enable from Shutdown to Output High	[†] RZH(SHDN)	Figure 8			2200	ns
Receiver Enable from Shutdown to Output Low	tRZL(SHDN)	Figure 8			2200	ns
Time to Shutdown	tshdn		50	340	700	ns

Note 1: µDFN devices production tested at +25°C. Overtemperature limits are generated by design.

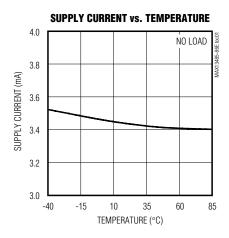
Note 2: All currents into the device are positive. All currents out of the device are negative. All voltages referred to device ground, unless otherwise noted.

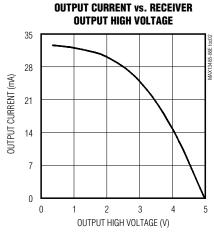
Note 3: ΔV_{OD} and ΔV_{OC} are the changes in V_{OD} and V_{OC} when the DI input changes states.

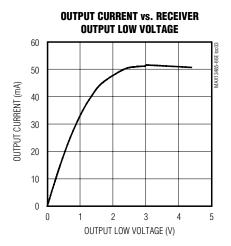
Note 4: The short-circuit output current applied to peak current just prior to foldback current limiting. The short-circuit foldback output current applies during current limiting to allow a recovery from bus contention.

_Typical Operating Characteristics

($V_{CC} = +5V$, $T_A = +25$ °C, unless otherwise noted.)

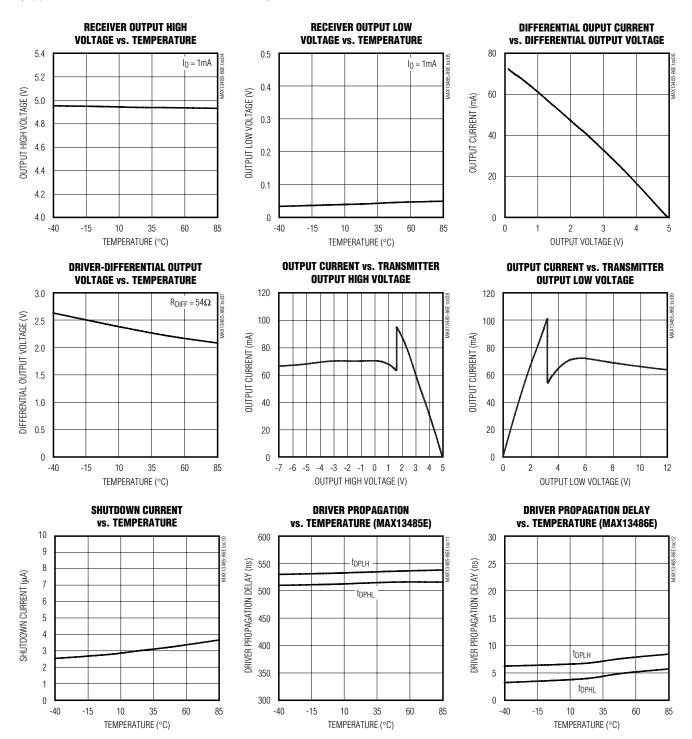






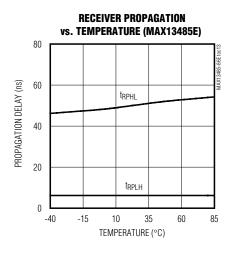
_Typical Operating Characteristics (continued)

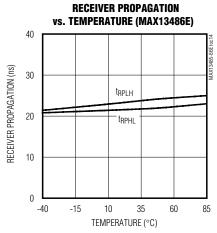
 $(V_{CC} = +5V, T_A = +25^{\circ}C, unless otherwise noted.)$

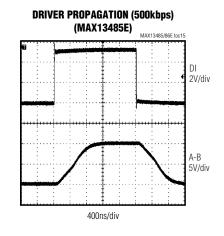


Typical Operating Characteristics (continued)

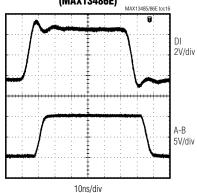
($V_{CC} = +5V$, $T_A = +25$ °C, unless otherwise noted.)



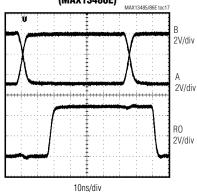




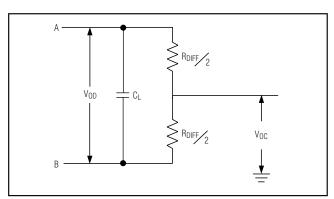
DRIVER PROPAGATION (16Mbps) (MAX13486E)



RECEIVER PROPAGATION (16Mbps) (MAX13486E)



Test Circuits and Waveforms



DI A VID RDIFF CL

Figure 1. Driver DC Test Load

Figure 2. Driver Timing Test Circuit

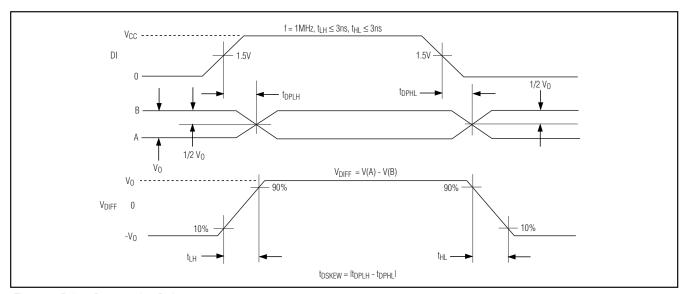


Figure 3. Driver Propagation Delays

Test Circuits and Waveforms (continued)

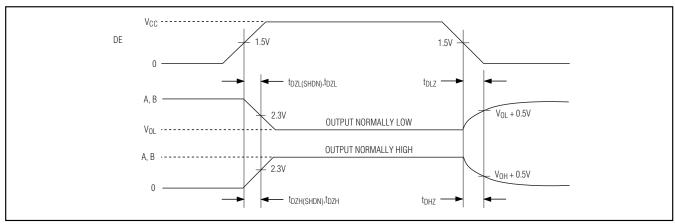


Figure 4. Driver Enable and Disable Times

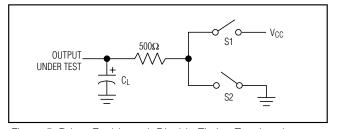


Figure 5. Driver-Enable and -Disable-Timing Test Load

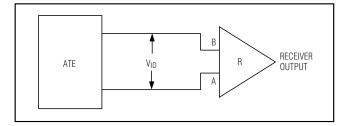


Figure 6. Receiver Propagation Delay Test Circuit

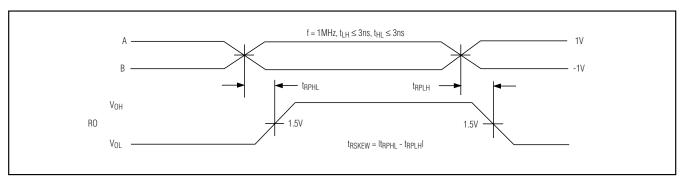


Figure 7. Receiver Propagation Delays

Pin Description

PIN	NAME	FUNCTION
1	RO	Receiver Output
2	RE	Receiver Output Enable. Drive \overline{RE} low to enable RO. RO is high impedance when \overline{RE} is high. Drive \overline{RE} high and DE low to enter low-power shutdown mode. \overline{RE} is a hot-swap input (see the <i>Hot-Swap Capability</i> section for more details).
3	DE	Driver Output Enable. Drive DE high to enable the driver outputs. These outputs are high-impedance when DE is low. Drive $\overline{\text{RE}}$ high and DE low to enter low-power shutdown mode. DE is a hot-swap input (see the <i>Hot-Swap Capability</i> section for more details).
4	DI	Driver Input. Drive DI low to force noninverting output low and inverting output high. Drive DI high to force noninverting output high and inverting output low (see the <i>Function Tables</i>).
5	GND	Ground
6	А	Noninverting Receiver Input and Noninverting Driver Output
7	В	Inverting Receiver Input and Inverting Driver Output
8	Vcc	Positive Supply, V _{CC} = +5V ±5%. Bypass V _{CC} to GND with a 0.1µF capacitor.

Function Tables

TRANSMITTING								
	INPUT		OUT	PUT				
RE	DE	DI	В	А				
Χ	1	1	0	1				
Χ	1	0	1	0				
0	0	Χ	HIGH IMPEDANCE	HIGH IMPEDANCE				
1	0	Χ	SHUTDOWN					

RECEIVING						
	INP	OUTPUT				
RE	DE	A-B	RO			
0	Х	≥ -50mV	1			
0	Х	≤ -200mV	0			
0	Х	OPEN/SHORT	1			
1	1	X	HIGH IMPEDANCE			
1	0	Х	SHUTDOWN			

X = Don't care, shutdown mode, driver, and receiver outputs are in high impedance.

Test Circuits and Waveforms (continued)

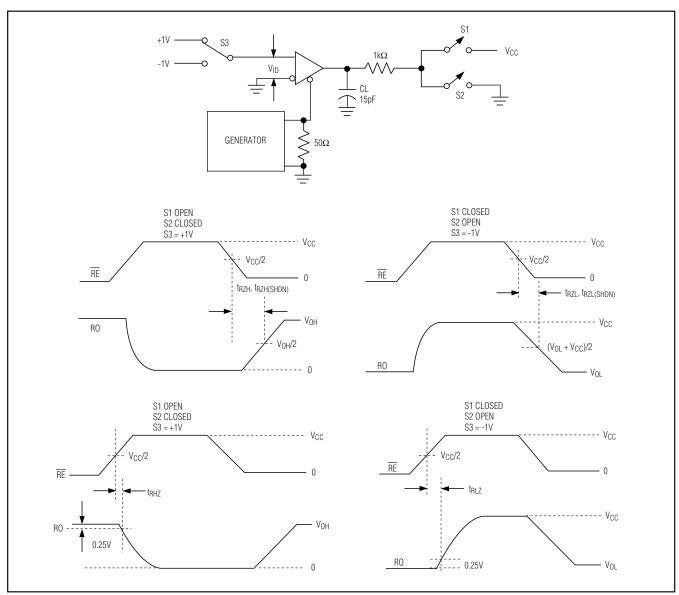


Figure 8. Receiver Enable and Disable Times

Detailed Description

The MAX13485E/MAX13486E half-duplex, high-speed transceivers for RS-485/RS-422 communication contain one driver and one receiver. These devices feature failsafe circuitry that guarantees a logic-high receiver output when receiver inputs are open or shorted, or when they are connected to a terminated transmission line with all drivers disabled (see the Fail-Safe section). The MAX13485E/MAX13486E also feature a hot-swap capability allowing line insertion without erroneous data transfer (see the Hot-Swap Capability section). The MAX13485E features reduced slew-rate drivers that minimize EMI and reduce reflections caused by improperly terminated cables, allowing error-free transmission up to 500kbps. The MAX13486E driver slew rate is not limited, making transmit speeds up to 16Mbps possible.

Fail-Safe

The MAX13485E/MAX13486E guarantee a logic-high receiver output when the receiver inputs are shorted or open, or when they are connected to a terminated transmission line with all drivers disabled. This is done by setting the receiver input threshold between -50mV and -200mV. If the differential receiver input voltage (A - B) is greater than or equal to -50mV, RO is logic-high. If (A - B) is less than or equal to -200mV, RO is logic-low. In the case of a terminated bus with all transmitters disabled, the receiver's differential input voltage is pulled to 0V by the termination. With the receiver thresholds of the MAX13485E/MAX13486E, this results is a logic-high with a 50mV minimum noise margin. Unlike previous fail-safe devices, the -50mV to -200mV threshold complies with the ±200mV EIA/TIA-485 standard.

Hot-Swap Capability Hot-Swap Inputs

When circuit boards are inserted into a hot or powered backplane, differential disturbances to the data bus can lead to data errors. Upon initial circuit-board insertion, the data communication processor undergoes its own power-up sequence. During this period, the processor's logic-output drivers are high impedance and are unable to drive the DE and $\overline{\text{RE}}$ inputs of these devices to a defined logic level. Leakage currents up to $\pm 10 \mu \text{A}$ from the high impedance state of the processor's logic drivers could cause standard CMOS enable inputs of a transceiver to drift to an incorrect logic level. Additionally, parasitic circuit-board capacitance could cause coupling of VCC or GND to the enable inputs. Without the hot-swap capability, these factors could improperly enable the transceiver's driver or receiver.

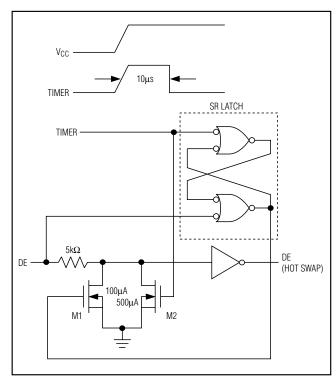


Figure 9. Simplified Structure of the Driver Enable Pin (DE)

When V_{CC} rises, an internal pulldown circuit holds DE low and \overline{RE} high. After the initial power-up sequence, the pulldown circuit becomes transparent, resetting the hot-swap tolerable input.

Hot-Swap Input Circuitry

The enable inputs feature hot-swap capability. At the input there are two nMOS devices, M1 and M2 (Figure 9). When VCC ramps from zero, an internal 7µs timer turns on M2 and sets the SR latch, which also turns on M1. Transistors M2, a 1.5mA current sink, and M1, a 500 μ A current sink, pull DE to GND through a $5k\Omega$ resistor. M2 is designed to pull DE to the disabled state against an external parasitic capacitance up to 100pF that can drive DE high. After 7µs, the timer deactivates M2 while M1 remains on, holding DE low against tristate leakages that can drive DE high. M1 remains on until an external source overcomes the required input current. At this time, the SR latch resets and M1 turns off. When M1 turns off, DE reverts to a standard highimpedance CMOS input. Whenever VCC drops below 1V, the hot-swap input is reset.

For RE there is a complementary circuit employing two pMOS devices pulling RE to VCC.

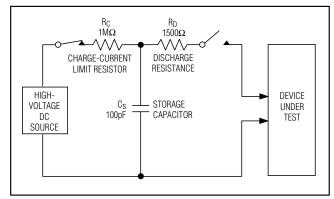


Figure 10a. Human Body ESD Test Model

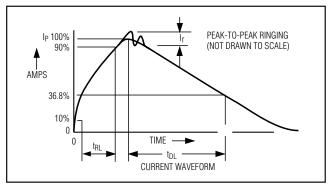


Figure 10b. Human Body Current Waveform

±15V ESD Protection

As with all Maxim devices, ESD-protection structures are incorporated on all pins to protect against electrostatic discharges encountered during handling and assembly. The driver outputs and receiver inputs of the MAX13485E/MAX13486E have extra protection against static electricity. Maxim's engineers have developed state-of-the-art structures to protect these pins against ESD of ±15kV without damage. The ESD structures withstand high ESD in all states: normal operation, shutdown, and powered down. After an ESD event, the MAX13485E/MAX13486E keep working without latchup or damage.

ESD protection can be tested in various ways. The transmitter outputs and receiver inputs of the MAX13485E/MAX13486E are characterized for protection to the following limits:

- ±15kV using the Human Body Model
- ±15kV using the Air Gap Discharge Method specified in IEC 61000-4-2 (MAX13485E only)

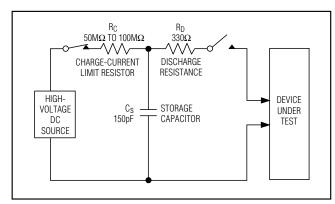


Figure 10c. ICE 61000-4-2 ESD Test Model

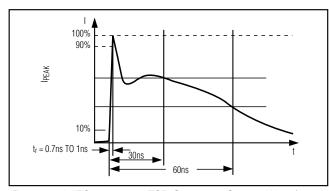


Figure 10d. IEC 61000-4-2 ESD Generator Current Waveform

ESD Test Conditions

ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test setup, test methodology, and test results.

Human Body Model

Figure 10a shows the Human Body Model, and Figure 10b shows the current waveform it generates when discharged into a low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the test device through a $1.5 \mathrm{k}\Omega$ resistor.

IEC 61000-4-2

The IEC 61000-4-2 standard covers ESD testing and performance of finished equipment. However, it does not specifically refer to integrated circuits. The MAX13485E/MAX13486E help equipment designs to meet IEC 61000-4-2, without the need for additional ESD-protection components.

The major difference between tests done using the Human Body Model and IEC 61000-4-2 is higher peak current in IEC 61000-4-2 because series resistance is lower in the IEC 61000-4-2 model. Hence, the ESD

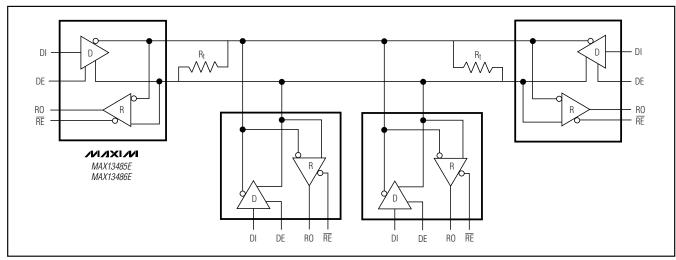


Figure 11. Typical Half-Duplex RS-485 Network

withstand voltage measured to IEC 61000-4-2 is generally lower than that measured using the Human Body Model. Figure 10c shows the IEC 61000-4-2 model, and Figure 10d shows the current waveform for the IEC 61000-4-2 ESD Contact Discharge test.

Machine Model

The machine model for ESD tests all pins using a 200pF storage capacitor and zero discharge resistance.

The objective is to emulate the stress caused when I/O pins are contacted by handling equipment during test and assembly. Of course, all pins require this protection, not just RS-485 inputs and outputs.

The air-gap test involves approaching the device with a charged probe. The contact-discharge method connects the probe to the device before the probe is energized.

_Applications Information

128 Transceivers on the Bus

The standard RS-485 receiver input impedance is $12k\Omega$ (1-unit load), and the standard driver can drive up to 32-unit loads. The MAX13485E/MAX13486E have a 1/4-unit load receiver input impedance (48k Ω), allowing up to 128 transceivers to be connected in parallel on one communication line. Any combination of these devices, as well as other RS-485 transceivers with a total of 32-unit loads or fewer, can be connected to the line.

Reduced EMI and Reflections

The MAX13485E features reduced slew-rate drivers that minimize EMI and reduce reflections caused by improperly terminated cables, allowing error-free data transmission up to 500kbps.

Low-Power Shutdown Mode

Low-power shutdown mode is initiated by bringing both \overline{RE} high and DE low. In shutdown, the devices draw a maximum of 10µA of supply current.

RE and DE can be driven simultaneously. The devices are guaranteed not to enter shutdown if RE is high and DE is low for less than 50ns. If the inputs are in this state for at least 700ns, the devices are guaranteed to enter shutdown.

Enable times t_{ZH} and t_{ZL} (see the *Switching Characteristics*) assume the devices were not in a low-power shutdown state. Enable times $t_{ZH(SHDN)}$ and $t_{ZL(SHDN)}$ assume the devices were in shutdown state. It takes drivers and receivers longer to become enabled from low-power shutdown mode ($t_{ZH(SHDN)}$), $t_{ZL(SHDN)}$) than from driver-/receiver-disable mode (t_{ZH} , t_{ZL}).

Line Length

The RS-485/RS-422 standard covers line lengths up to 4000ft.

Typical Applications

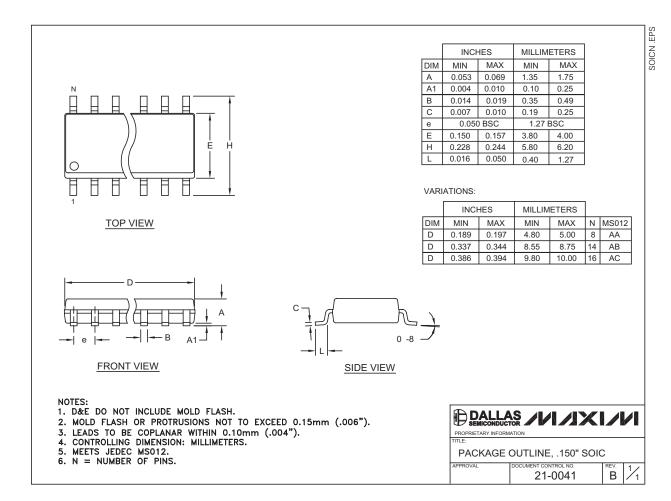
The MAX13485E/MAX13486E transceivers are designed for half-duplex, bidirectional data communications on multipoint bus transmission lines. Figure 11 shows typical network applications circuits. To minimize reflections, terminate the line at both ends in its characteristic impedance, and keep stub lengths off the main line as short as possible. The slew-rate-limited MAX13485E is more tolerant of imperfect termination.

Chip Information

PROCESS: BICMOS

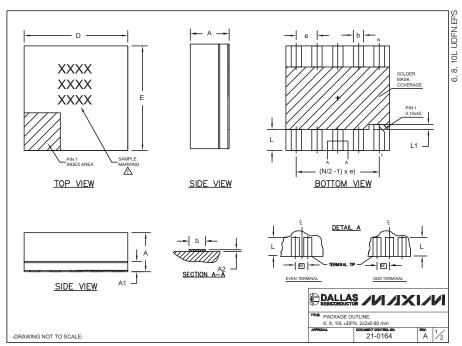
Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



Package Information (continued)

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A A1 A2	MIN.			
A1		NOM.	MAX.	
	0.70	0.75	0.80	
A2	0.15	0.20	0.25	
	0.020	0.025	0.035	
D	1.95	2.00	2.05	
E	1.95	2.00	2.05	
L	0.30	0.40	0.50	
L1	0).10 REF.		
L622-1	6	0.65 BSC		1.30 REF.
PKG. CODE	N	е	b	(N/2 -1) x e
L822-1	8	0.50 BSC		1.50 REF.
LUZZ-1	+-			1.60 REF.
L1022-1	1 10	0.40 BSC	0.20-0.03	

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